

# BFP450

Linear Low Noise Silicon Bipolar RF Transistor

## Datasheet

Revision 1.2, 2013-07-29

**Edition 2013-07-29**

**Published by  
Infineon Technologies AG  
81726 Munich, Germany**

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**BFP450, Linear Low Noise Silicon Bipolar RF Transistor**

**Revision History: 2013-07-29, Revision 1.2**

Page	Subjects (changes since previous revision)
	This datasheet replaces the revision from 2012-09-11. The product itself has not been changed and the device characteristics remain unchanged. Only the product description and information available in the datasheet have been expanded and updated.

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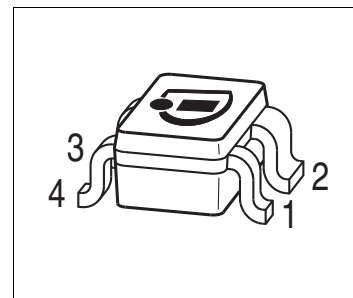
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## 1 Product Brief

The BFP450 is a high linearity wideband NPN bipolar RF transistor. The collector design supports voltages up to  $V_{CEO} = 4.5\text{ V}$  and currents up to  $I_C = 170\text{ mA}$ . With its high linearity at currents as low as 50 mA the device supports energy efficient designs. The typical transition frequency is approximately 24 GHz, hence the device offers high power gain at frequencies up to 3 GHz in amplifier applications. The device is housed in an easy to use plastic package with visible leads.

## 2 Features

- Highly linear low noise driver amplifier for all RF frontends up to 3 GHz
- Based on Infineon’s reliable high volume 25 GHz silicon bipolar technology
- Output compression point  $OP_{1dB} = 19$  dBm at 90 mA, 3 V, 1.9 GHz, 50  $\Omega$  system
- Output 3rd order intermodulation point  $OIP3 = 31$  dBm at 90 mA, 3 V, 1.9 GHz, 50  $\Omega$  system
- Maximum available gain  $G_{ma} = 15.5$  dB at 50 mA, 3 V, 1.9 GHz
- Minimum noise figure  $NF_{min} = 1.7$  dB at 50 mA, 3 V, 1.9 GHz
- Pb-free (RoHS compliant) and halogen-free package with visible leads
- Qualification report according to AEC-Q101 available



### Applications Examples

Driver amplifier

- ISM bands 434 and 868 MHz
- 1.9 GHz cordless phones
- CATV LNA

Transmitter driver amplifier

- 2.4 GHz WLAN and Bluetooth

Output stage LNA for active antennas

- TV, GPS, SDARS, 2.4 GHz WLAN, etc

Suitable for 3 - 5.5 GHz oscillators

**Attention: ESD (Electrostatic discharge) sensitive device, observe handling precautions**

Product Name	Package	Pin Configuration				Marking
BFP450	SOT343	1 = B	2 = E	3 = C	4 = E	ANs



### 3 Maximum Ratings

Table 3-1 Maximum Ratings

Parameter	Symbol	Values		Unit	Note / Test Condition
		Min.	Max.		
Collector emitter voltage	$V_{CEO}$	–	4.5	V	Open base $T_A = 25\text{ °C}$
		–	4.1	V	$T_A = -55\text{ °C}$
Collector emitter voltage	$V_{CES}$	–	15	V	E-B short circuited
Collector base voltage	$V_{CBO}$	–	15	V	Open emitter
Emitter base voltage	$V_{EBO}$	–	1.5	V	Open collector
Collector current	$I_C$	–	170	mA	–
Base current	$I_B$	–	10	mA	–
Total power dissipation <sup>1)</sup>	$P_{tot}$	–	500	mW	$T_S \leq 90\text{ °C}$
Junction temperature	$T_J$	–	150	°C	–
Storage temperature	$T_{Stg}$	-55	150	°C	–

1)  $T_S$  is the soldering point temperature.  $T_S$  is measured on the emitter lead at the soldering point of the pcb.

**Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit.**

## 4 Thermal Characteristics

Table 4-1 Thermal Resistance

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Junction - soldering point <sup>1)</sup>	$R_{thJS}$	–	120	–	K/W	–

1) For the definition of  $R_{thJS}$  please refer to Application Note AN077 (Thermal Resistance Calculation)

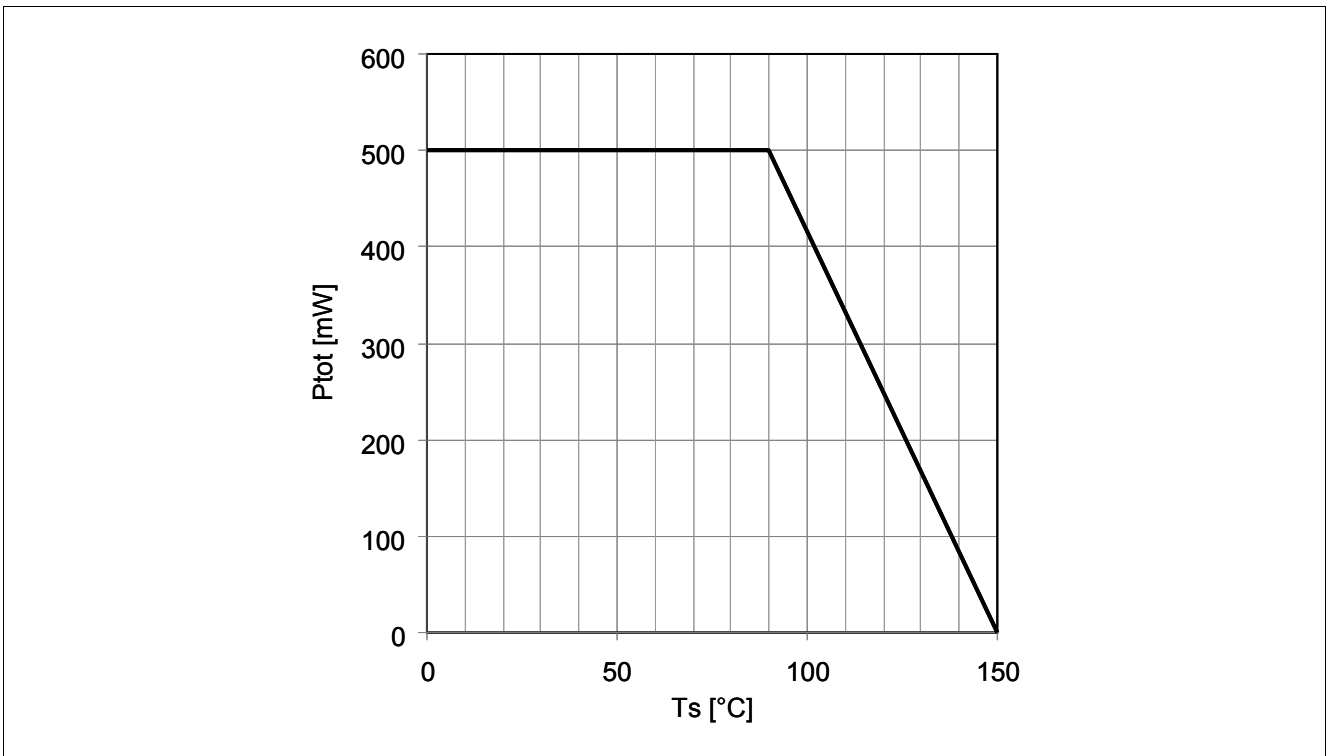


Figure 4-1 Total Power Dissipation  $P_{tot} = f(T_s)$

## 5 Electrical Characteristics

### 5.1 DC Characteristics

**Table 5-1 DC Characteristics at  $T_A = 25\text{ °C}$** 

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Collector emitter breakdown voltage	$V_{(BR)CEO}$	4.5	5	–	V	$I_C = 1\text{ mA}$ , $I_B = 0$ Open base
Collector emitter leakage current	$I_{CES}$	–	–	1 <sup>1)</sup>	$\mu\text{A}$	$V_{CE} = 15\text{ V}$ , $V_{BE} = 0$ $V_{CE} = 3\text{ V}$ , $V_{BE} = 0$ E-B short circuited
		–	1	30 <sup>1)</sup>	nA	
Collector base leakage current	$I_{CBO}$	–	1	30 <sup>1)</sup>	nA	$V_{CB} = 3\text{ V}$ , $I_E = 0$ Open emitter
Emitter base leakage current	$I_{EBO}$	–	0.05	3 <sup>1)</sup>	$\mu\text{A}$	$V_{EB} = 0.5\text{ V}$ , $I_C = 0$ Open collector
DC current gain	$h_{FE}$	60	95	130		$V_{CE} = 4\text{ V}$ , $I_C = 50\text{ mA}$ $V_{CE} = 3\text{ V}$ , $I_C = 90\text{ mA}$ Pulse measured
		50	85	120		

1) Maximum values not limited by the device but the short cycle time of the 100% test

### 5.2 General AC Characteristics

**Table 5-2 General AC Characteristics at  $T_A = 25\text{ °C}$** 

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Transition frequency	$f_T$	18	24	–	GHz	$V_{CE} = 3\text{ V}$ , $I_C = 90\text{ mA}$ , $f = 1\text{ GHz}$
Collector base capacitance	$C_{CB}$	–	0.48	0.8	pF	$V_{CB} = 3\text{ V}$ , $V_{BE} = 0\text{ V}$ $f = 1\text{ MHz}$ Emitter grounded
Collector emitter capacitance	$C_{CE}$	–	1.2	–	pF	$V_{CE} = 3\text{ V}$ , $V_{BE} = 0\text{ V}$ $f = 1\text{ MHz}$ Base grounded
Emitter base capacitance	$C_{EB}$	–	1.7	–	pF	$V_{EB} = 0.5\text{ V}$ , $V_{CB} = 0\text{ V}$ $f = 1\text{ MHz}$ Collector grounded

### 5.3 Frequency Dependent AC Characteristics

Measurement setup is a test fixture with Bias T's in a 50 Ω system,  $T_A = 25\text{ °C}$

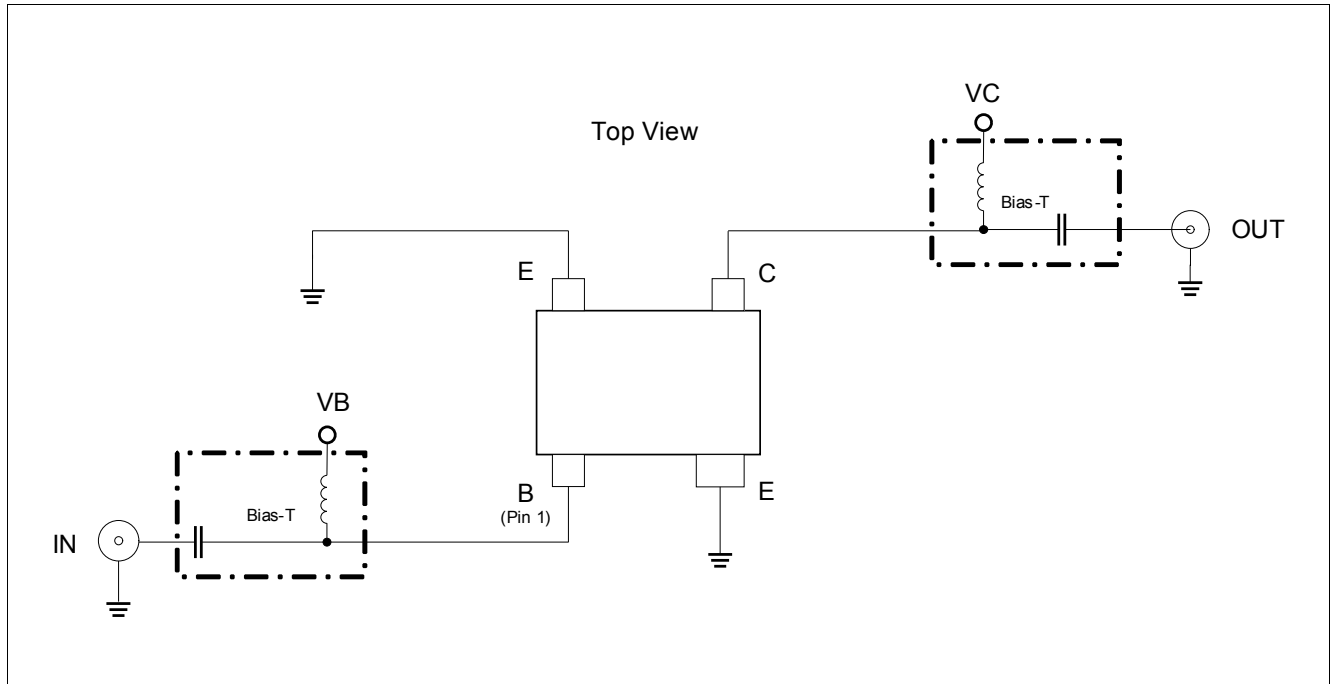


Figure 5-1 BFP450 Testing Circuit

Table 5-3 AC Characteristics,  $V_{CE} = 3\text{ V}$ ,  $f = 150\text{ MHz}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
<b>Maximum power gain</b>					dB	
High linearity operation point	$G_{ms}$	–	34.5	–		$I_C = 50\text{ mA}$
Class A operation point	$G_{ms}$	–	35.5	–		$I_C = 90\text{ mA}$
<b>Transducer gain</b>					dB	$Z_S = Z_L = 50\text{ }\Omega$
High linearity operation point	$S_{21}$	–	33	–		$I_C = 50\text{ mA}$
Class A operation point	$S_{21}$	–	33.5	–		$I_C = 90\text{ mA}$
<b>Minimum noise figure</b>					dB	$Z_S = Z_{opt}$
Minimum noise figure	$NF_{min}$	–	1.55	–		$I_C = 50\text{ mA}$
Associated gain	$G_{ass}$	–	32	–		$I_C = 50\text{ mA}$
<b>Linearity</b>					dBm	$Z_S = Z_L = 50\text{ }\Omega$
1 dB gain compression point	$OP_{1dB}$	–	19	–		$I_C = 90\text{ mA}$
3rd order intercept point	$OIP3$	–	30.5	–		$I_C = 90\text{ mA}$

**Table 5-4 AC Characteristics,  $V_{CE} = 3\text{ V}$ ,  $f = 450\text{ MHz}$** 

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
<b>Maximum power gain</b>					dB	
High linearity operation point	$G_{ms}$	–	28.5	–		$I_C = 50\text{ mA}$
Class A operation point	$G_{ms}$	–	29	–		$I_C = 90\text{ mA}$
<b>Transducer gain</b>					dB	$Z_S = Z_L = 50\ \Omega$
High linearity operation point	$S_{21}$	–	25	–		$I_C = 50\text{ mA}$
Class A operation point	$S_{21}$	–	25	–		$I_C = 90\text{ mA}$
<b>Minimum noise figure</b>					dB	$Z_S = Z_{opt}$
Minimum noise figure	$NF_{min}$	–	1.55	–		$I_C = 50\text{ mA}$
Associated gain	$G_{ass}$	–	27.5	–		$I_C = 50\text{ mA}$
<b>Linearity</b>					dBm	$Z_S = Z_L = 50\ \Omega$
1 dB gain compression point	$OP_{1dB}$	–	19	–		$I_C = 90\text{ mA}$
3rd order intercept point	$OIP3$	–	30	–		$I_C = 90\text{ mA}$

**Table 5-5 AC Characteristics,  $V_{CE} = 3\text{ V}$ ,  $f = 900\text{ MHz}$** 

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
<b>Maximum power gain</b>					dB	
High linearity operation point	$G_{ms}$	–	23	–		$I_C = 50\text{ mA}$
Class A operation point	$G_{ms}$	–	23.5	–		$I_C = 90\text{ mA}$
<b>Transducer gain</b>					dB	$Z_S = Z_L = 50\ \Omega$
High linearity operation point	$S_{21}$	–	18.5	–		$I_C = 50\text{ mA}$
Class A operation point	$S_{21}$	–	19	–		$I_C = 90\text{ mA}$
<b>Minimum noise figure</b>					dB	$Z_S = Z_{opt}$
Minimum noise figure	$NF_{min}$	–	1.6	–		$I_C = 50\text{ mA}$
Associated gain	$G_{ass}$	–	23	–		$I_C = 50\text{ mA}$
<b>Linearity</b>					dBm	$Z_S = Z_L = 50\ \Omega$
1 dB gain compression point	$OP_{1dB}$	–	19	–		$I_C = 90\text{ mA}$
3rd order intercept point	$OIP3$	–	30.5	–		$I_C = 90\text{ mA}$

**Table 5-6 AC Characteristics,  $V_{CE} = 3\text{ V}$ ,  $f = 1.5\text{ GHz}$** 

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
<b>Maximum power gain</b>					dB	
High linearity operation point	$G_{ma}$	–	18	–		$I_C = 50\text{ mA}$
Class A operation point	$G_{ma}$	–	18	–		$I_C = 90\text{ mA}$
<b>Transducer gain</b>					dB	$Z_S = Z_L = 50\ \Omega$
High linearity operation point	$S_{21}$	–	14	–		$I_C = 50\text{ mA}$
Class A operation point	$S_{21}$	–	14	–		$I_C = 90\text{ mA}$
<b>Minimum noise figure</b>					dB	$Z_S = Z_{opt}$
Minimum noise figure	$NF_{min}$	–	1.65	–		$I_C = 50\text{ mA}$
Associated gain	$G_{ass}$	–	17	–		$I_C = 50\text{ mA}$
<b>Linearity</b>					dBm	$Z_S = Z_L = 50\ \Omega$
1 dB gain compression point	$OP_{1dB}$	–	19	–		$I_C = 90\text{ mA}$
3rd order intercept point	$OIP3$	–	31	–		$I_C = 90\text{ mA}$

**Table 5-7 AC Characteristics,  $V_{CE} = 3\text{ V}$ ,  $f = 1.9\text{ GHz}$** 

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
<b>Maximum power gain</b>					dB	
High linearity operation point	$G_{ma}$	–	15.5	–		$I_C = 50\text{ mA}$
Class A operation point	$G_{ma}$	–	15.5	–		$I_C = 90\text{ mA}$
<b>Transducer gain</b>					dB	$Z_S = Z_L = 50\ \Omega$
High linearity operation point	$S_{21}$	9.5	11.5	–		$I_C = 50\text{ mA}$
Class A operation point	$S_{21}$	–	11.5	–		$I_C = 90\text{ mA}$
<b>Minimum noise figure</b>					dB	$Z_S = Z_{opt}$
Minimum noise figure	$NF_{min}$	–	1.7	–		$I_C = 50\text{ mA}$
Associated gain	$G_{ass}$	–	14	–		$I_C = 50\text{ mA}$
<b>Linearity</b>					dBm	$Z_S = Z_L = 50\ \Omega$
1 dB gain compression point	$OP_{1dB}$	–	19	–		$I_C = 90\text{ mA}$
3rd order intercept point	$OIP3$	–	31	–		$I_C = 90\text{ mA}$

**Table 5-8 AC Characteristics,  $V_{CE} = 3\text{ V}$ ,  $f = 2.4\text{ GHz}$** 

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
<b>Maximum power gain</b>					dB	
High linearity operation point	$G_{ma}$	–	13.5	–		$I_C = 50\text{ mA}$
Class A operation point	$G_{ma}$	–	13.5	–		$I_C = 90\text{ mA}$
<b>Transducer gain</b>					dB	$Z_S = Z_L = 50\ \Omega$
High linearity operation point	$S_{21}$	–	9.5	–		$I_C = 50\text{ mA}$
Class A operation point	$S_{21}$	–	9.5	–		$I_C = 90\text{ mA}$
<b>Minimum noise figure</b>					dB	$Z_S = Z_{opt}$
Minimum noise figure	$NF_{min}$	–	1.8	–		$I_C = 50\text{ mA}$
Associated gain	$G_{ass}$	–	12	–		$I_C = 50\text{ mA}$
<b>Linearity</b>					dBm	$Z_S = Z_L = 50\ \Omega$
1 dB gain compression point	$OP_{1dB}$	–	19	–		$I_C = 90\text{ mA}$
3rd order intercept point	$OIP3$	–	30	–		$I_C = 90\text{ mA}$

**Table 5-9 AC Characteristics,  $V_{CE} = 3\text{ V}$ ,  $f = 3.5\text{ GHz}$** 

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
<b>Maximum power gain</b>					dB	
High linearity operation point	$G_{ma}$	–	10	–		$I_C = 50\text{ mA}$
Class A operation point	$G_{ma}$	–	10	–		$I_C = 90\text{ mA}$
<b>Transducer gain</b>					dB	$Z_S = Z_L = 50\ \Omega$
High linearity operation point	$S_{21}$	–	5.5	–		$I_C = 50\text{ mA}$
Class A operation point	$S_{21}$	–	6	–		$I_C = 90\text{ mA}$
<b>Minimum noise figure</b>					dB	$Z_S = Z_{opt}$
Minimum noise figure	$NF_{min}$	–	2.05	–		$I_C = 50\text{ mA}$
Associated gain	$G_{ass}$	–	9	–		$I_C = 50\text{ mA}$
<b>Linearity</b>					dBm	$Z_S = Z_L = 50\ \Omega$
1 dB gain compression point	$OP_{1dB}$	–	18.5	–		$I_C = 90\text{ mA}$
3rd order intercept point	$OIP3$	–	29.5	–		$I_C = 90\text{ mA}$

**Notes**

1. AC parameter limits verified by random sampling
2. In order to get the  $NF_{min}$  values stated in this chapter the test fixture losses have been subtracted from all measured result
3.  $OIP3$  value depends on termination of all intermodulation frequency components. Termination used for this measurement is  $50\ \Omega$  from 0.2 MHz to 12 GHz.

5.4 Characteristic DC Diagrams

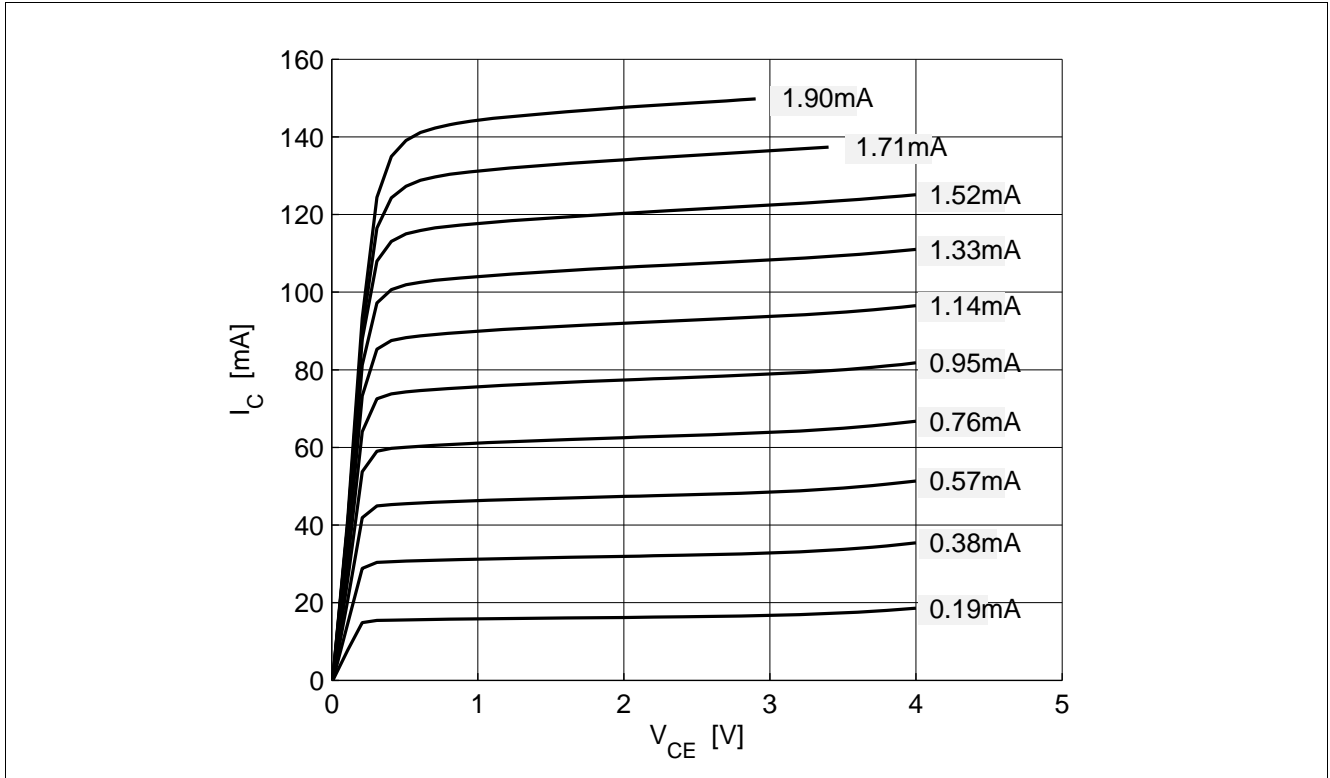


Figure 5-2 Collector Current vs. Collector Emitter Voltage  $I_C = f(V_{CE})$ ,  $I_B = \text{Parameter in mA}$

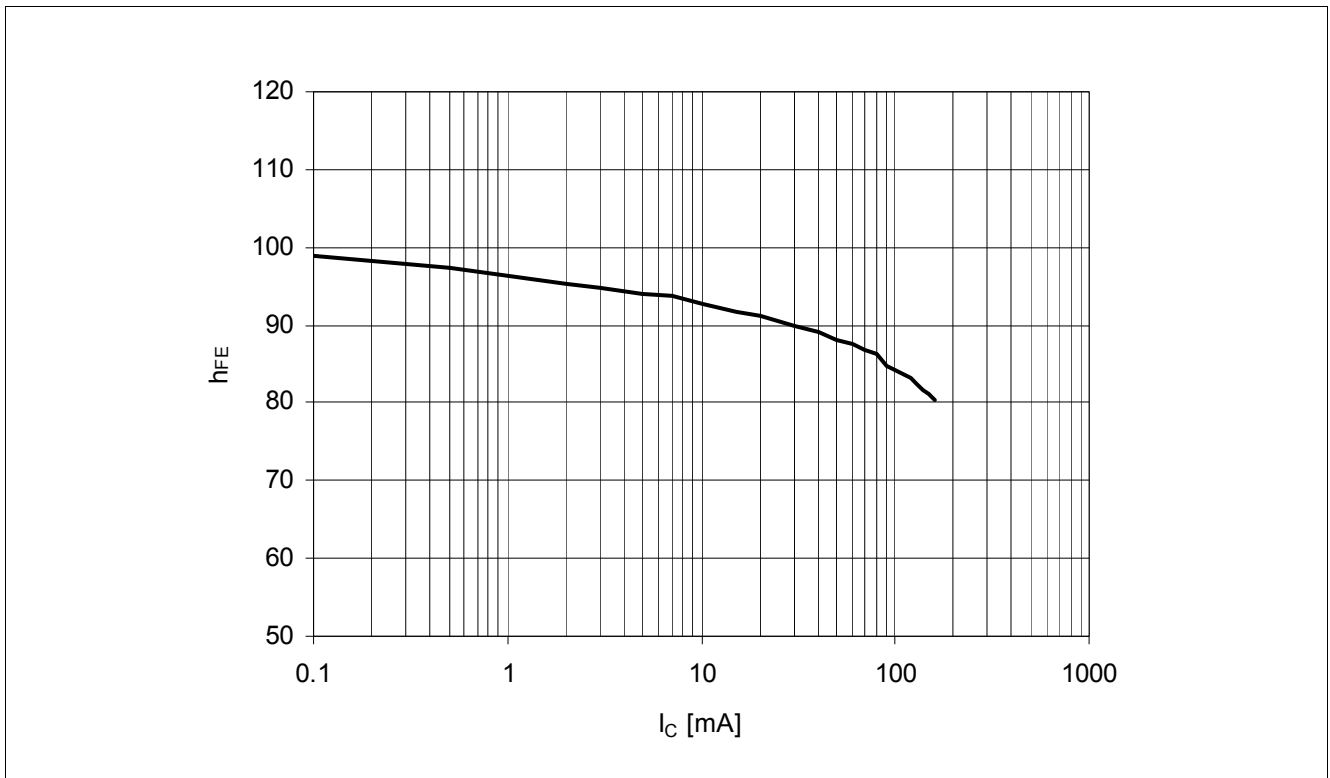


Figure 5-3 DC Current Gain  $h_{FE} = f(I_C)$ ,  $V_{CE} = 3 \text{ V}$



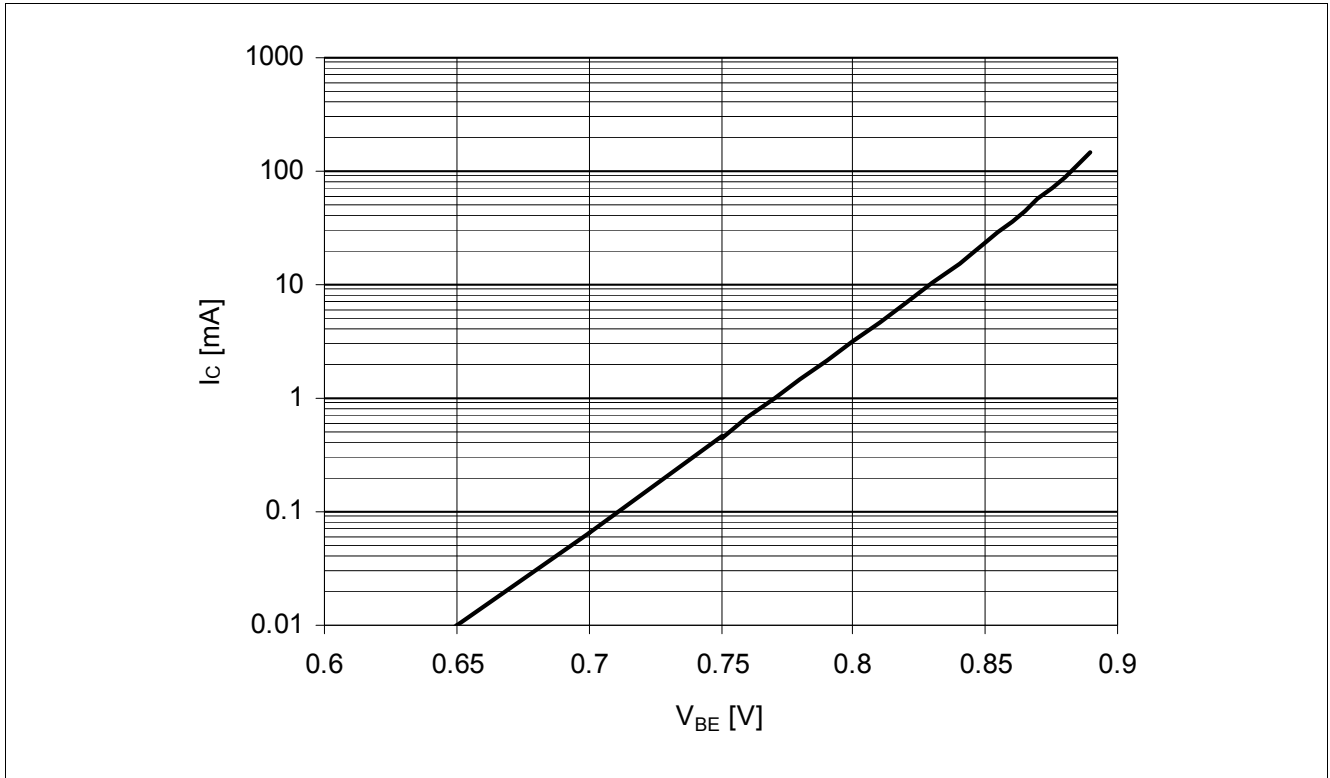


Figure 5-4 Collector Current vs. Base Emitter Voltage  $I_C = f(V_{BE})$ ,  $V_{CE} = 2\text{ V}$

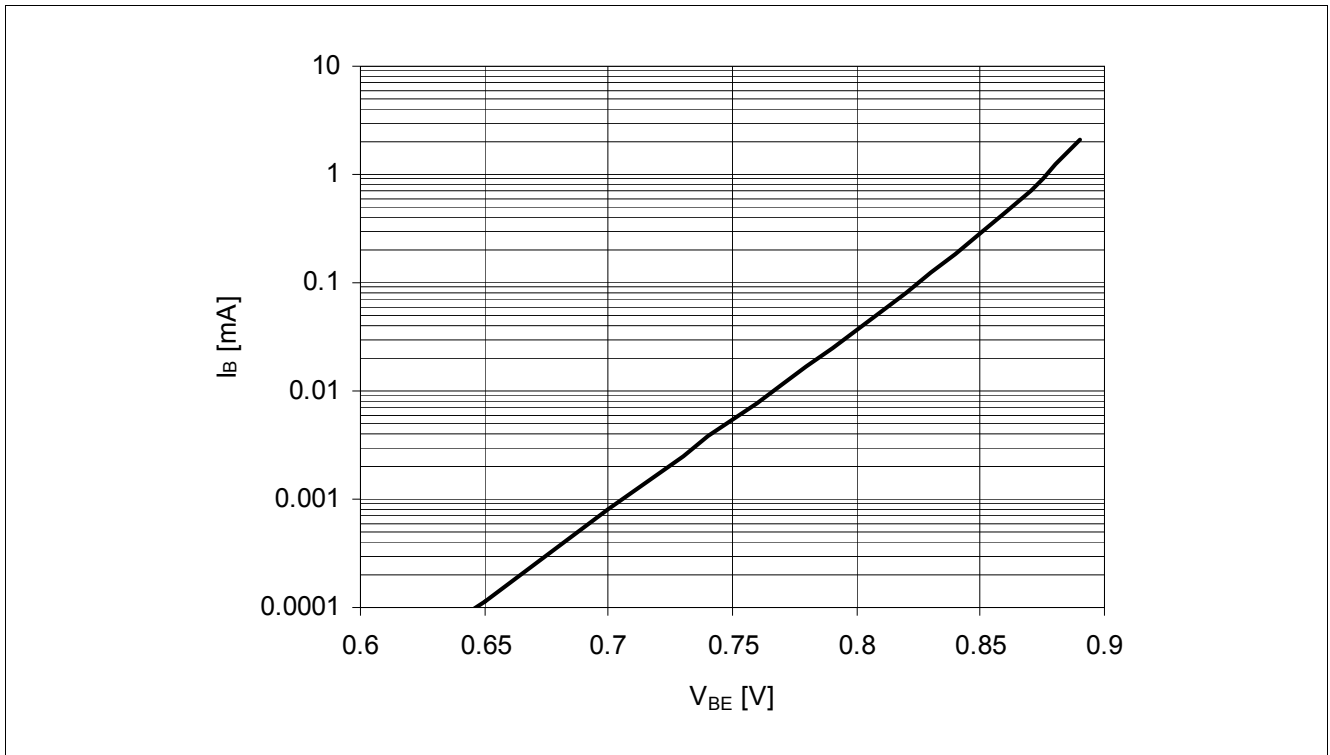


Figure 5-5 Base Current vs. Base Emitter Forward Voltage  $I_B = f(V_{BE})$ ,  $V_{CE} = 2\text{ V}$

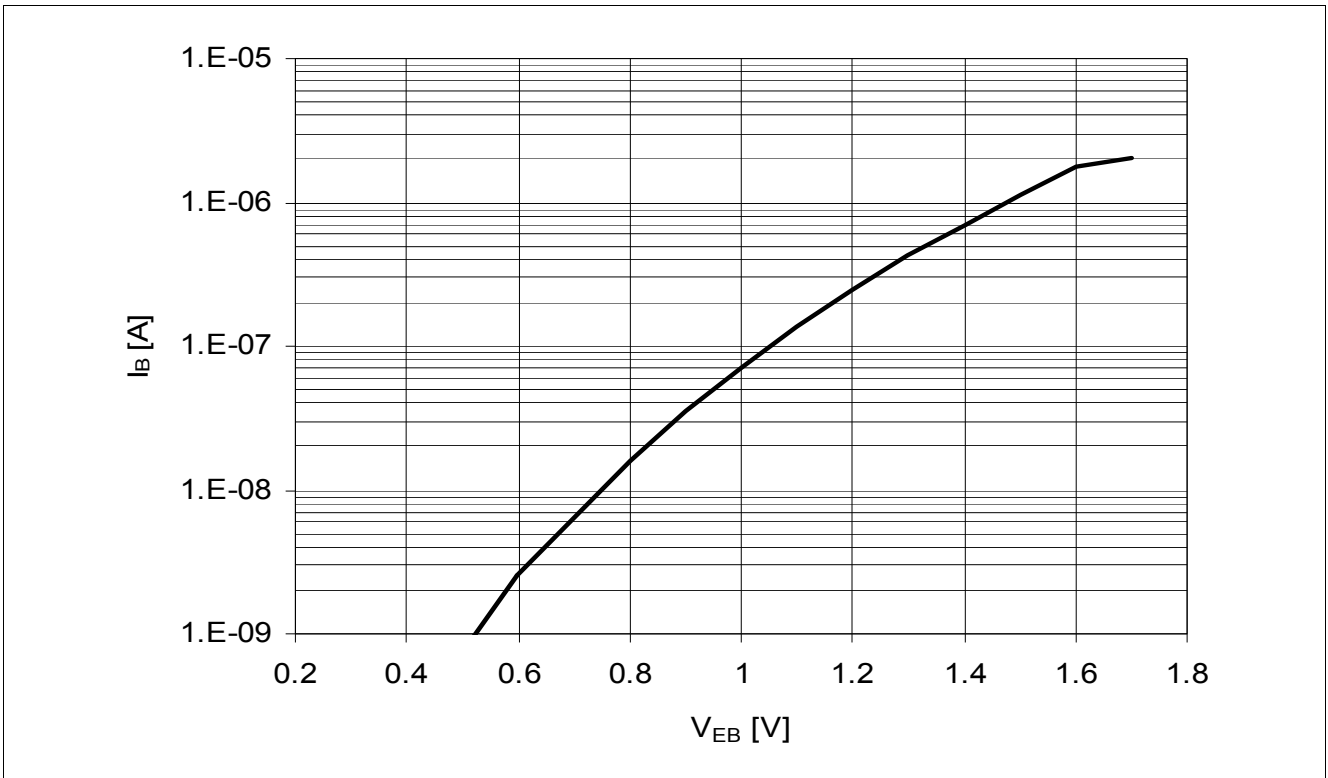


Figure 5-6 Base Current vs. Base Emitter Reverse Voltage  $I_B = f(V_{EB})$ ,  $V_{CE} = 2\text{ V}$

5.5 Characteristic AC Diagrams

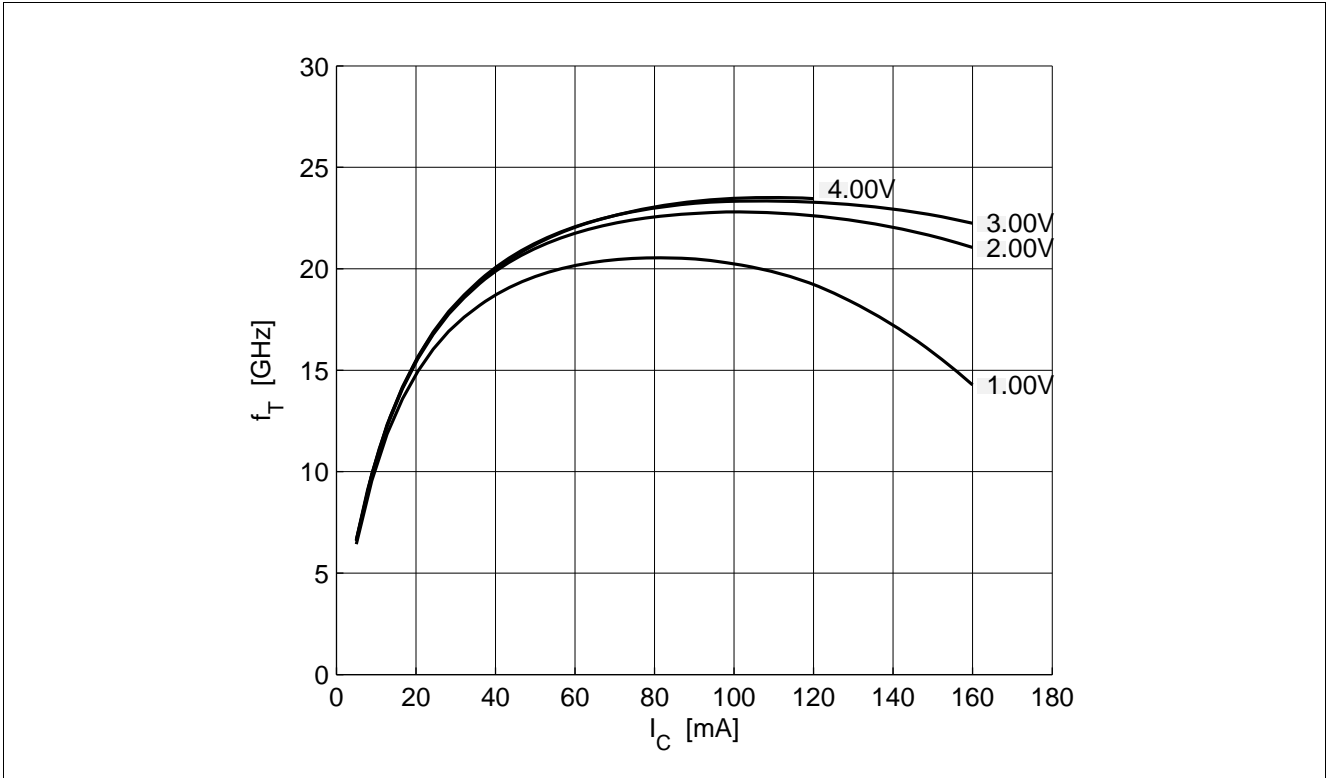


Figure 5-7 Transition Frequency  $f_T = f(I_C)$ ,  $f = 1 \text{ GHz}$ ,  $V_{CE} = \text{Parameter in V}$

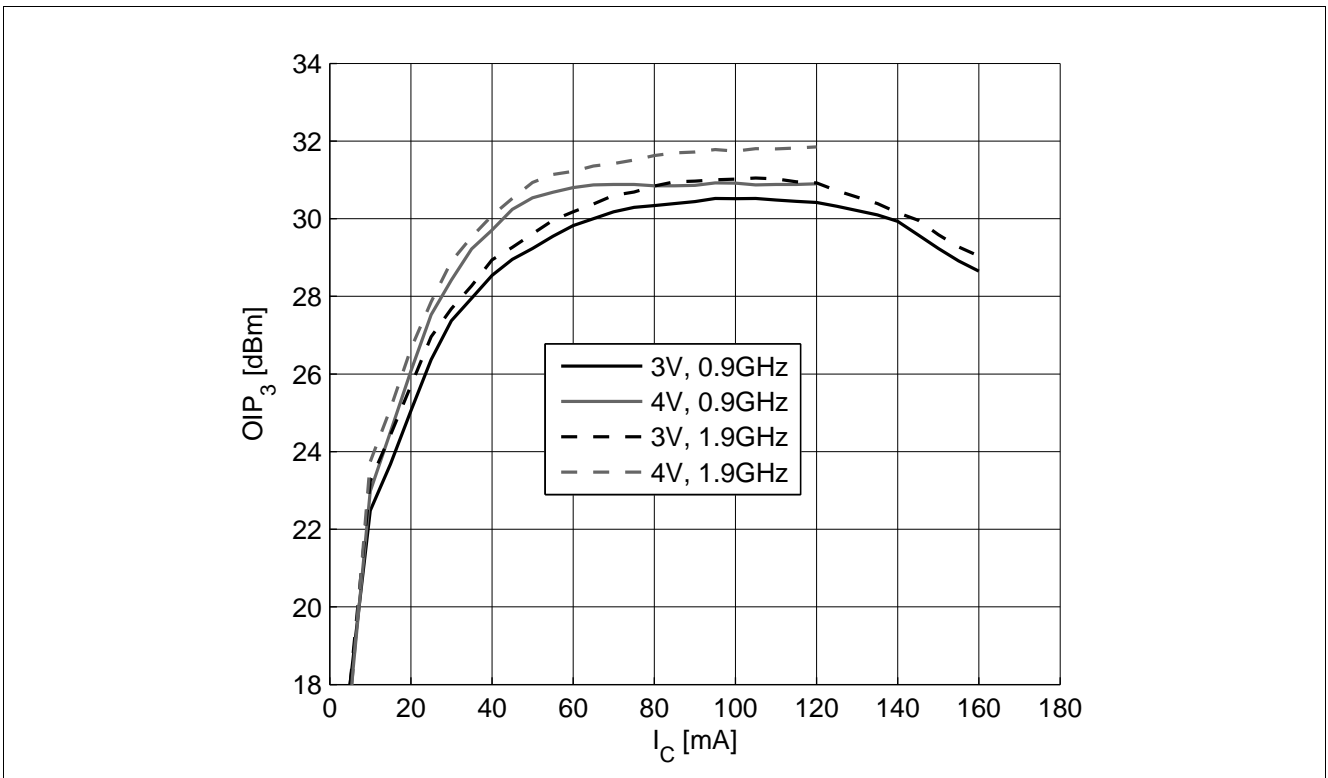


Figure 5-8 3rd Order Intercept Point  $OIP3 = f(I_C)$ ,  $Z_S = Z_L = 50 \Omega$ ,  $V_{CE}, f = \text{Parameters}$

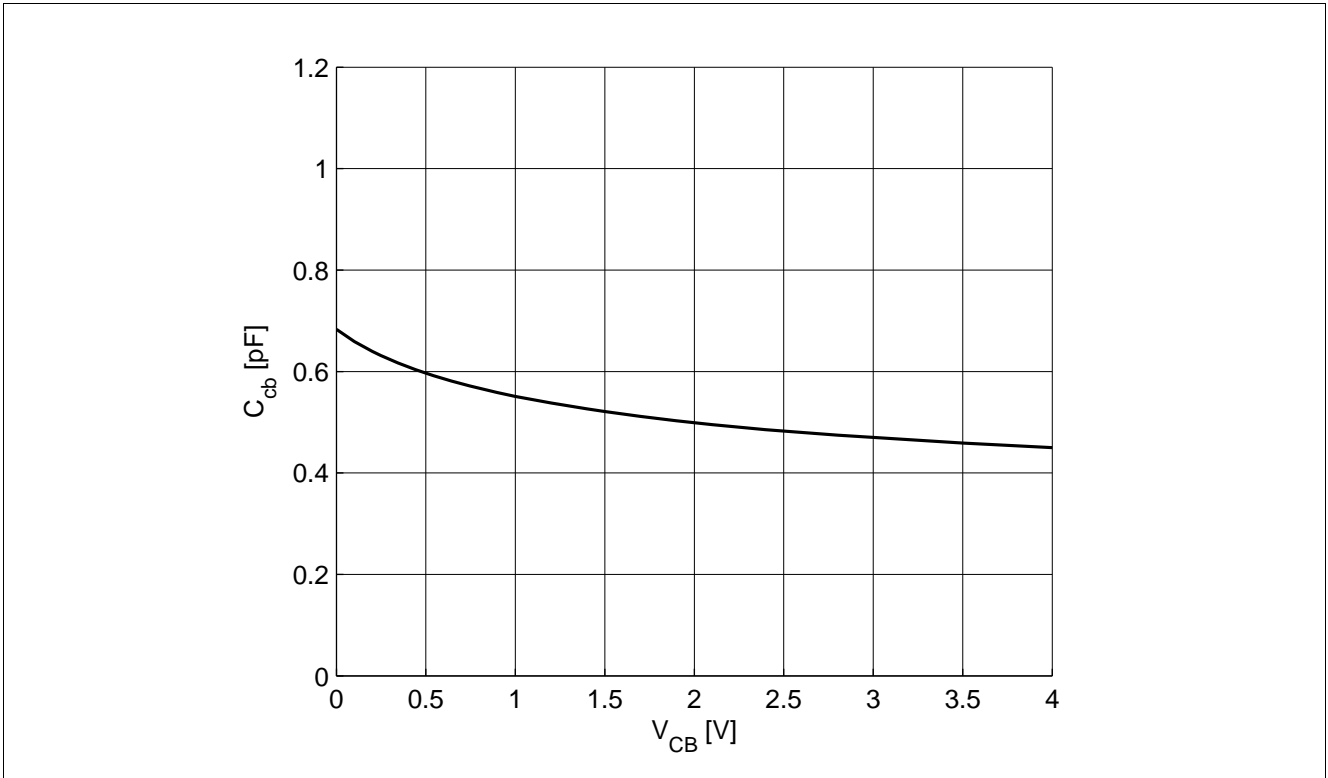


Figure 5-9 Collector Base Capacitance  $C_{CB} = f(V_{CB}), f = 1 \text{ MHz}$

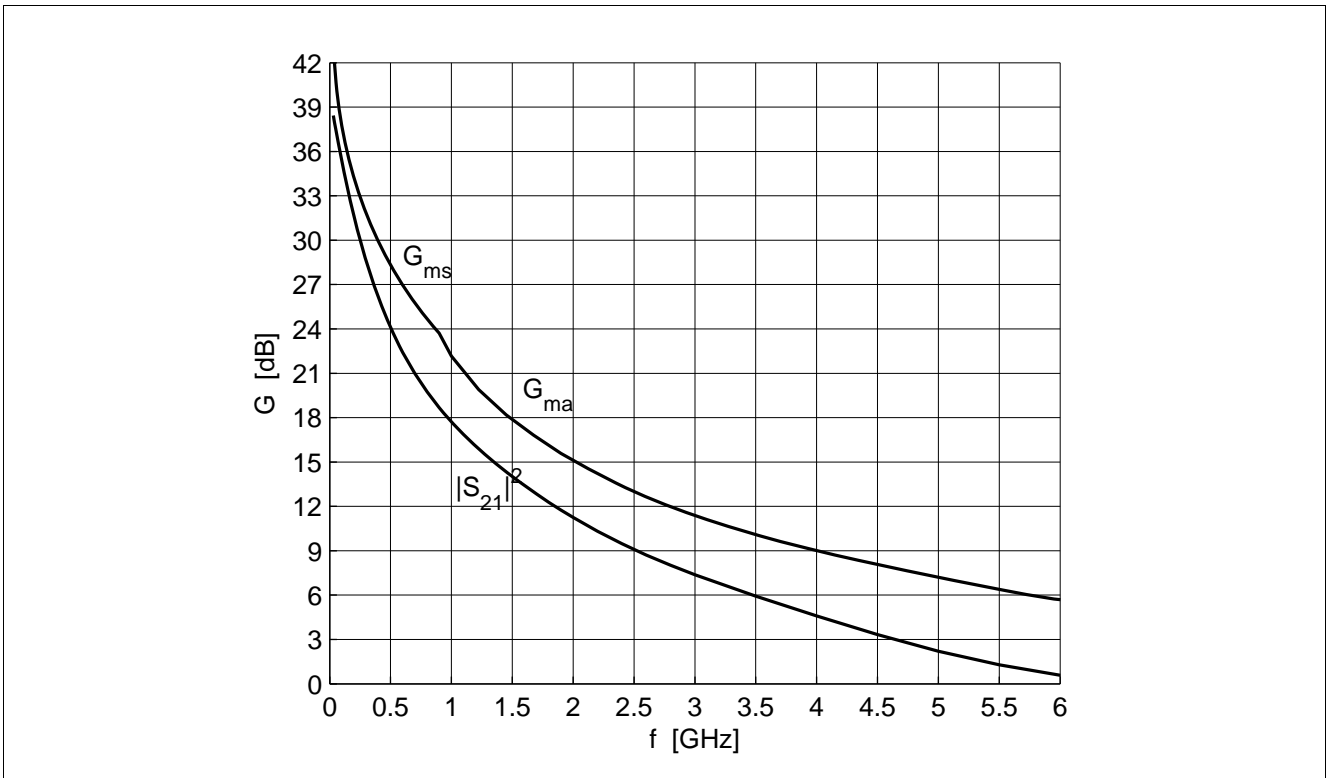


Figure 5-10 Gain  $G_{ma}, G_{ms}, |S_{21}|^2 = f(f), V_{CE} = 3 \text{ V}, I_C = 90 \text{ mA}$

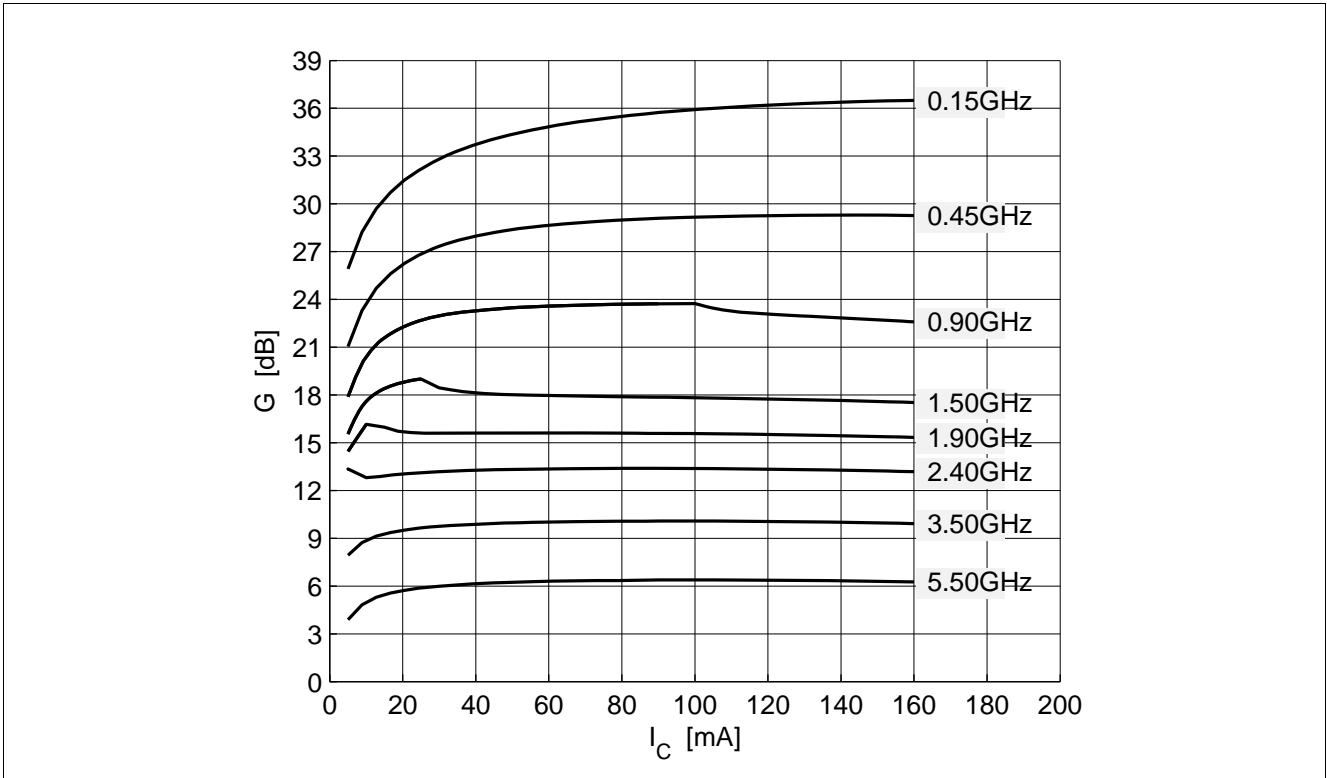


Figure 5-11 Maximum Power Gain  $G_{max} = f(I_C)$ ,  $V_{CE} = 3\text{ V}$ , = Parameter in GHz

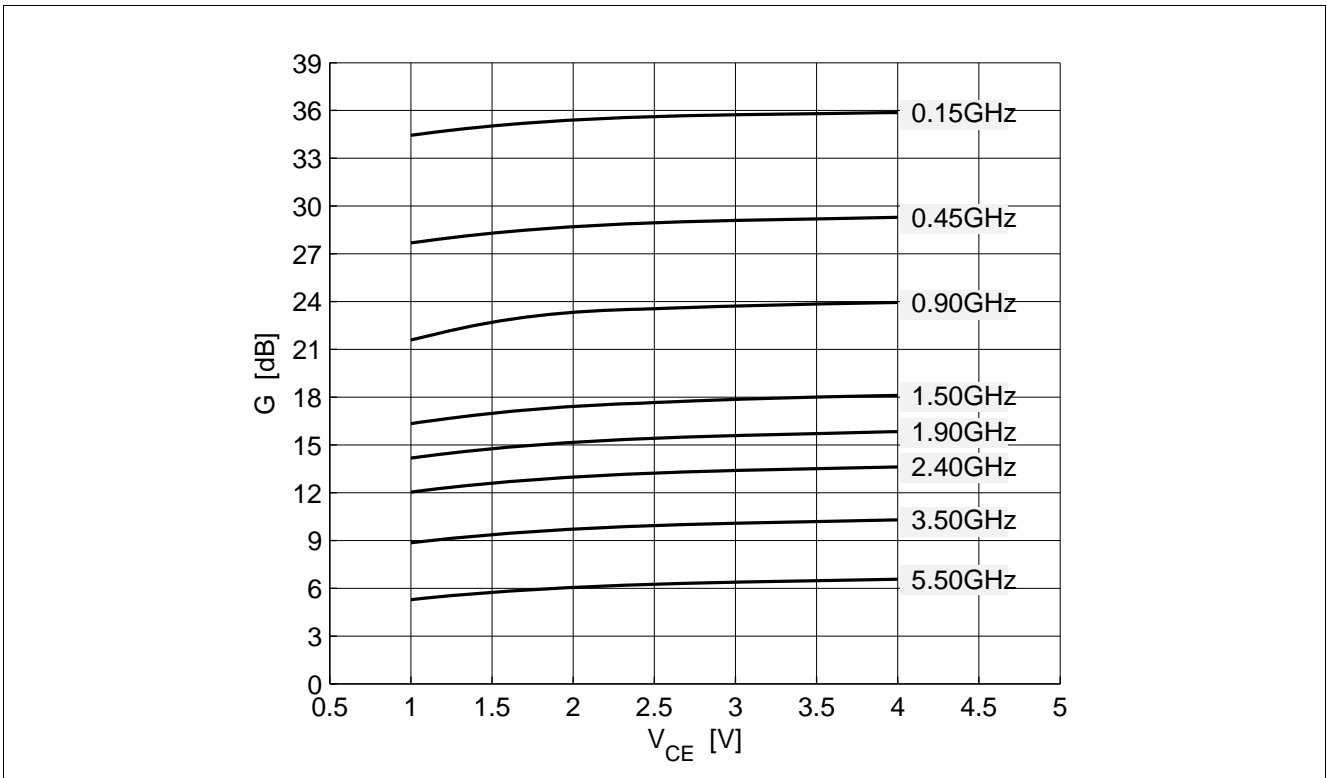


Figure 5-12 Maximum Power Gain  $G_{max} = f(V_{CE})$ ,  $I_C = 90\text{ mA}$ , = Parameter in GHz

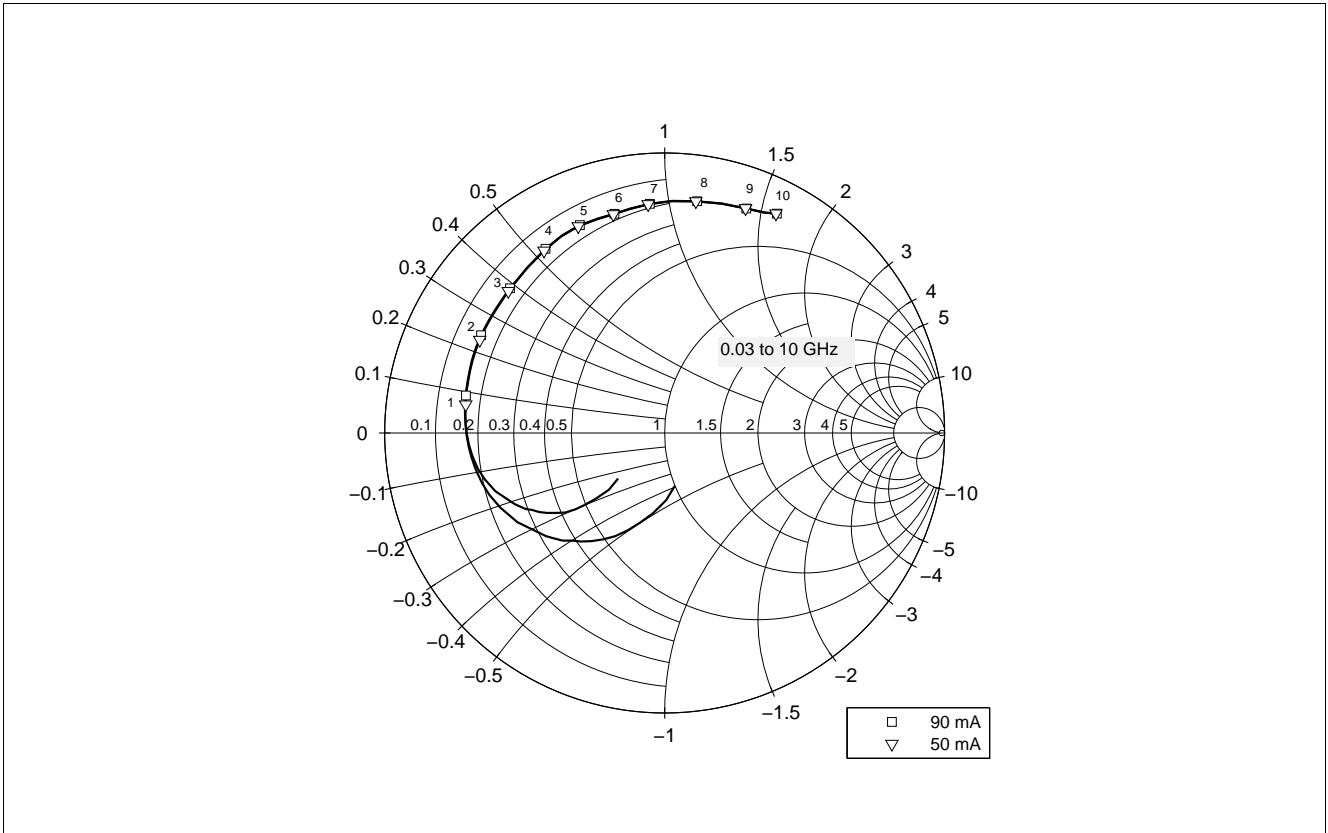


Figure 5-13 Input Matching  $S_{11} = f(f)$ ,  $V_{CE} = 3\text{ V}$ ,  $I_C = 50 / 90\text{ mA}$

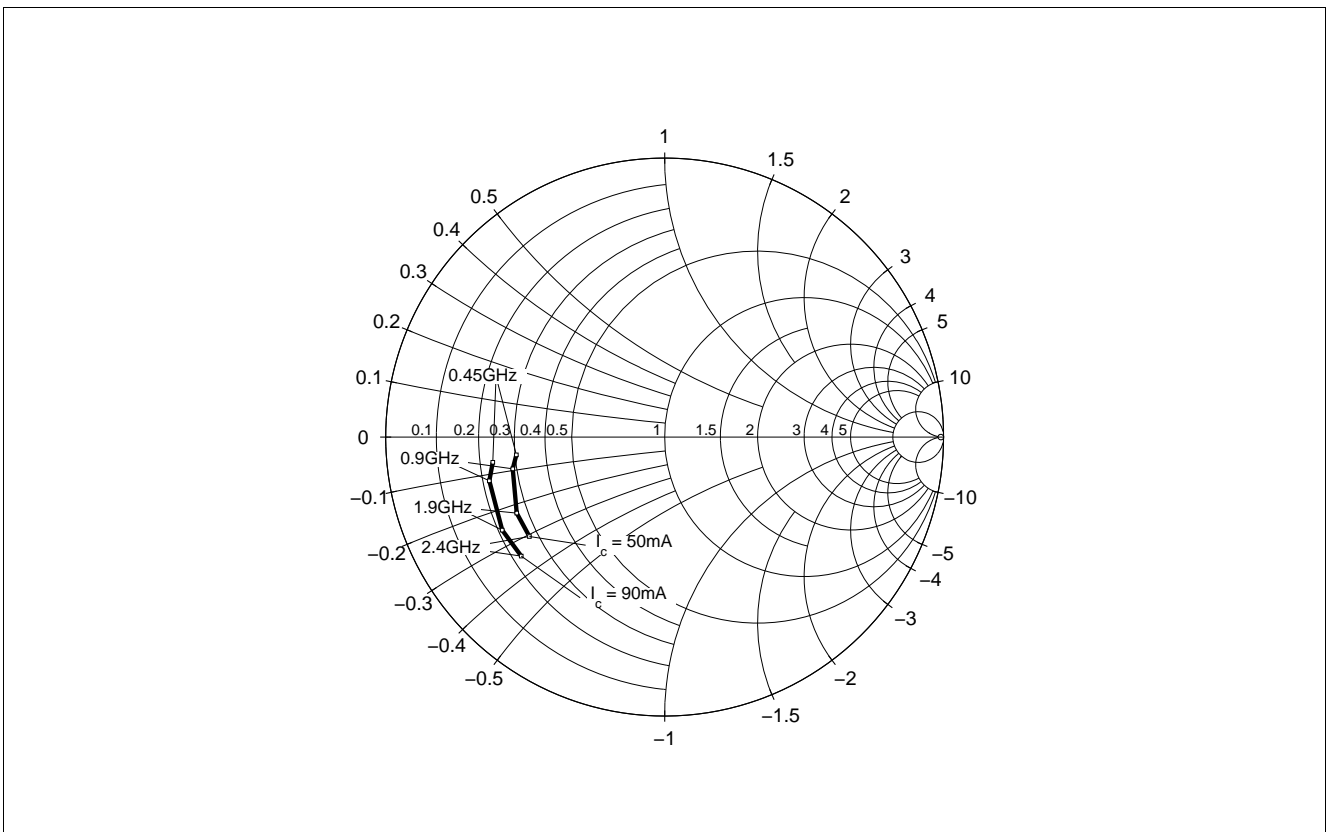


Figure 5-14 Source Impedance for Minimum Noise Figure  $= f(f)$ ,  $V_{CE} = 3\text{ V}$ ,  $I_C = 50 / 90\text{ mA}$

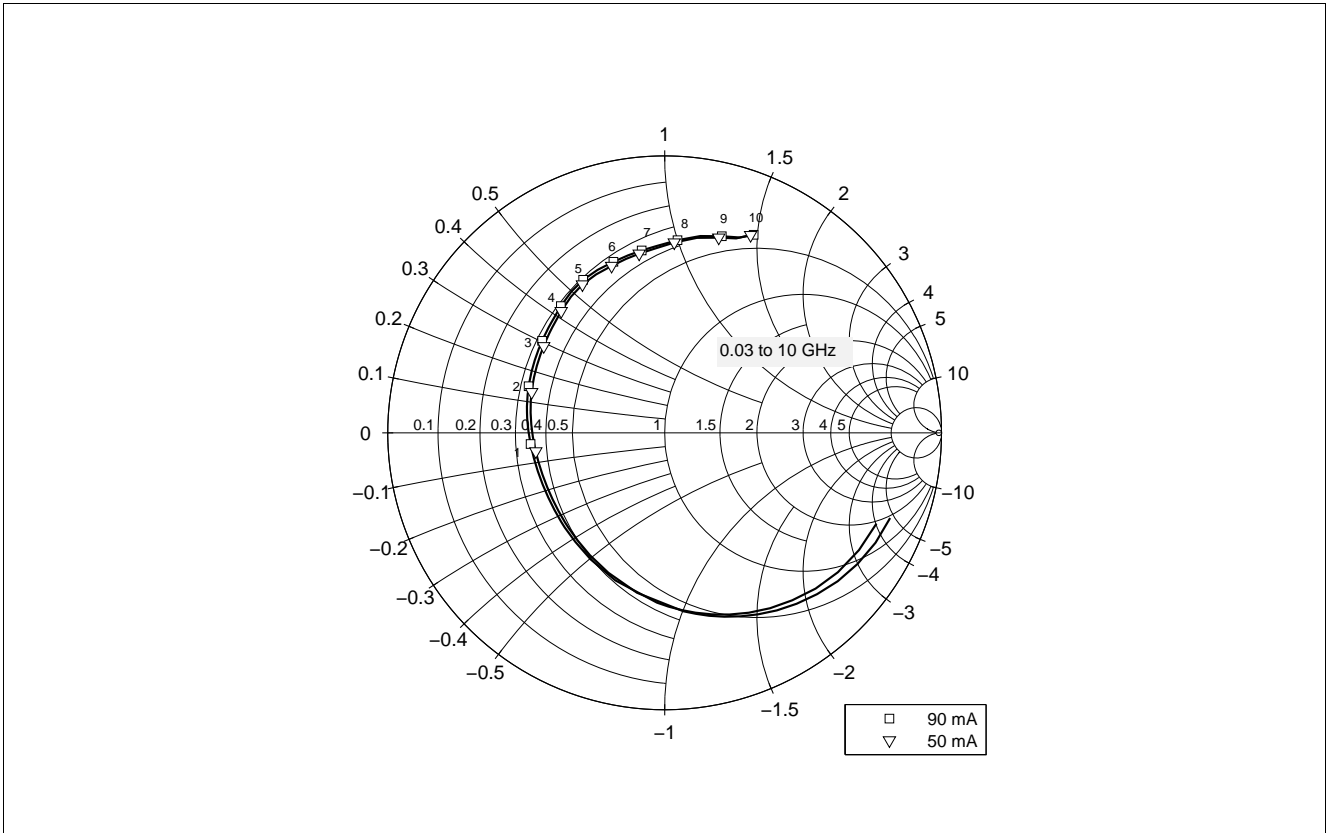


Figure 5-15 Output Matching  $S_{22} = f(f)$ ,  $V_{CE} = 3\text{ V}$ ,  $I_C = 50 / 90\text{ mA}$

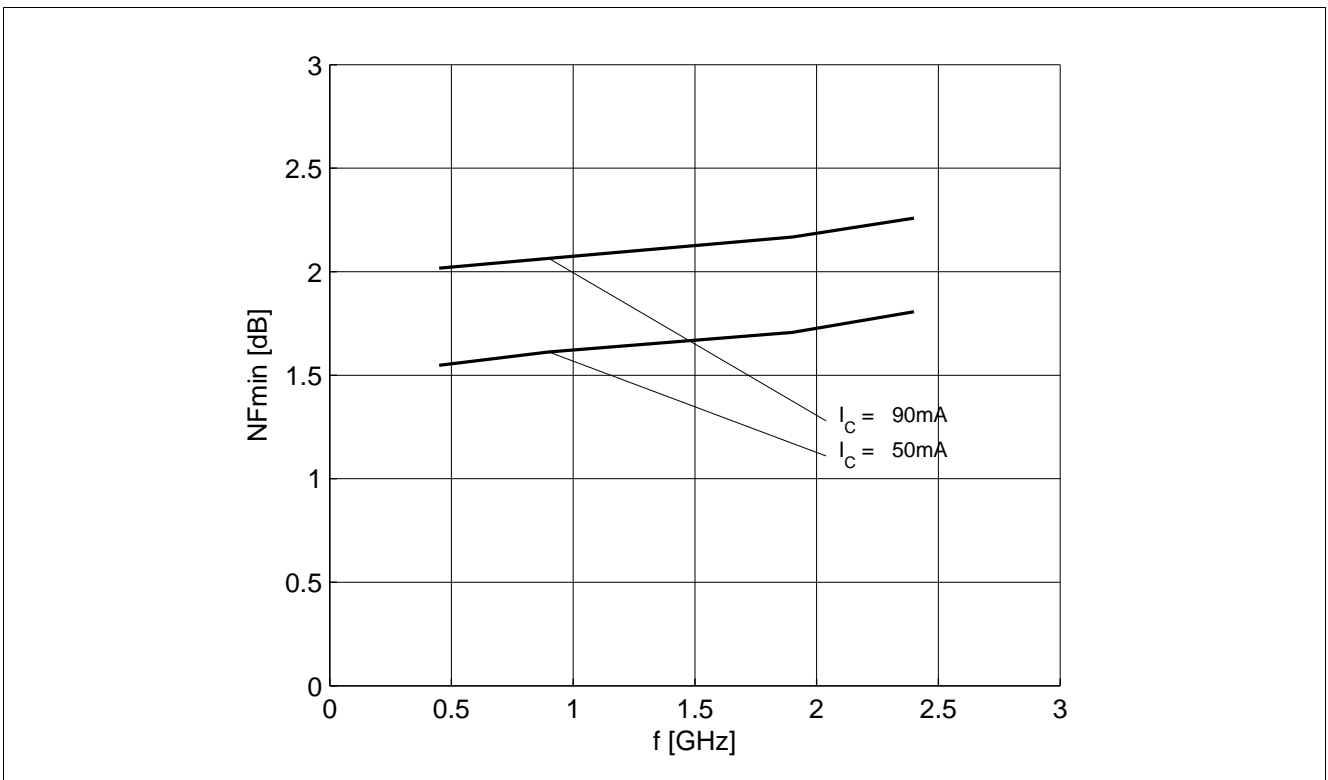


Figure 5-16 Noise Figure  $NF_{min} = f(f)$ ,  $V_{CE} = 3\text{ V}$ ,  $I_C = 50 / 90\text{ mA}$ ,  $Z_S = Z_{opt}$

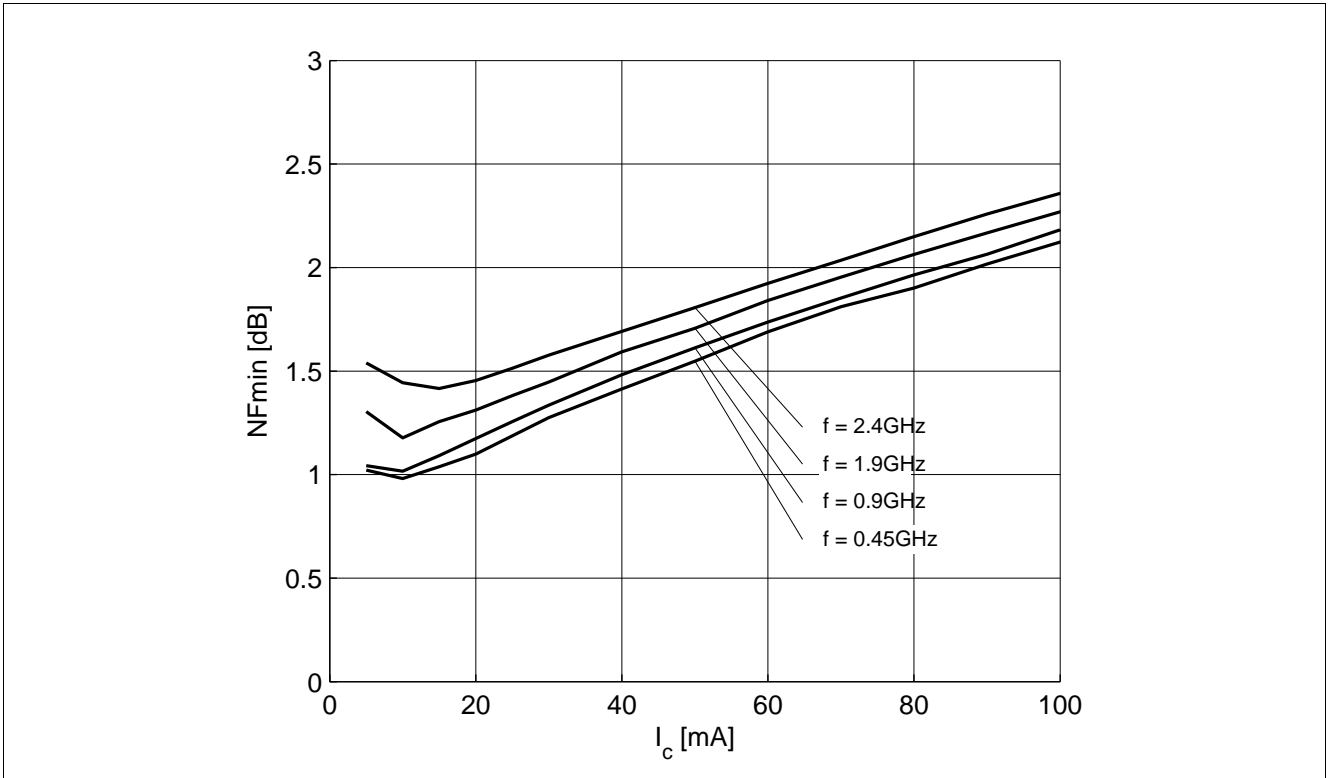


Figure 5-17 Noise Figure  $NF_{min} = f(I_C)$ ,  $V_{CE} = 3\text{ V}$ ,  $Z_S = Z_{opt}$  Parameter in GHz

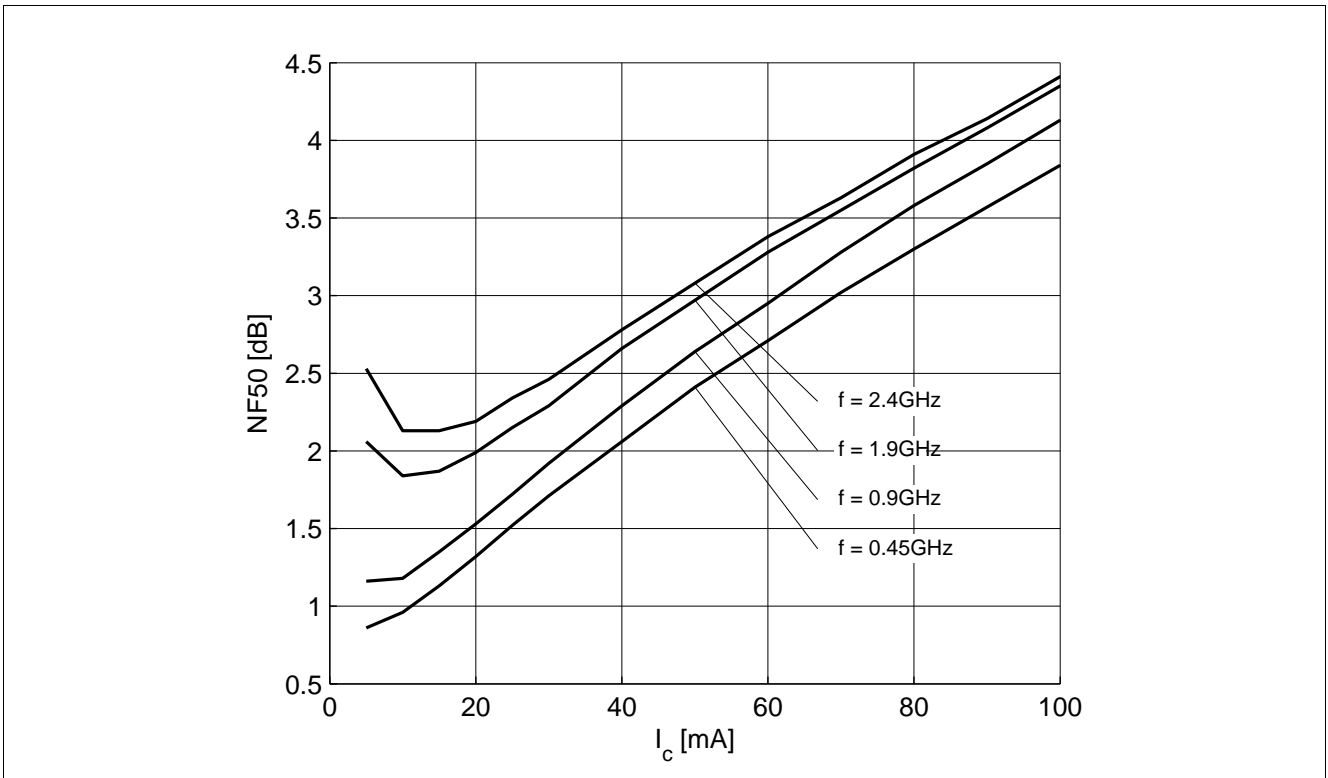


Figure 5-18 Noise Figure  $NF_{50} = f(I_C)$ ,  $V_{CE} = 3\text{ V}$ ,  $Z_S = 50\ \Omega$  Parameter in GHz



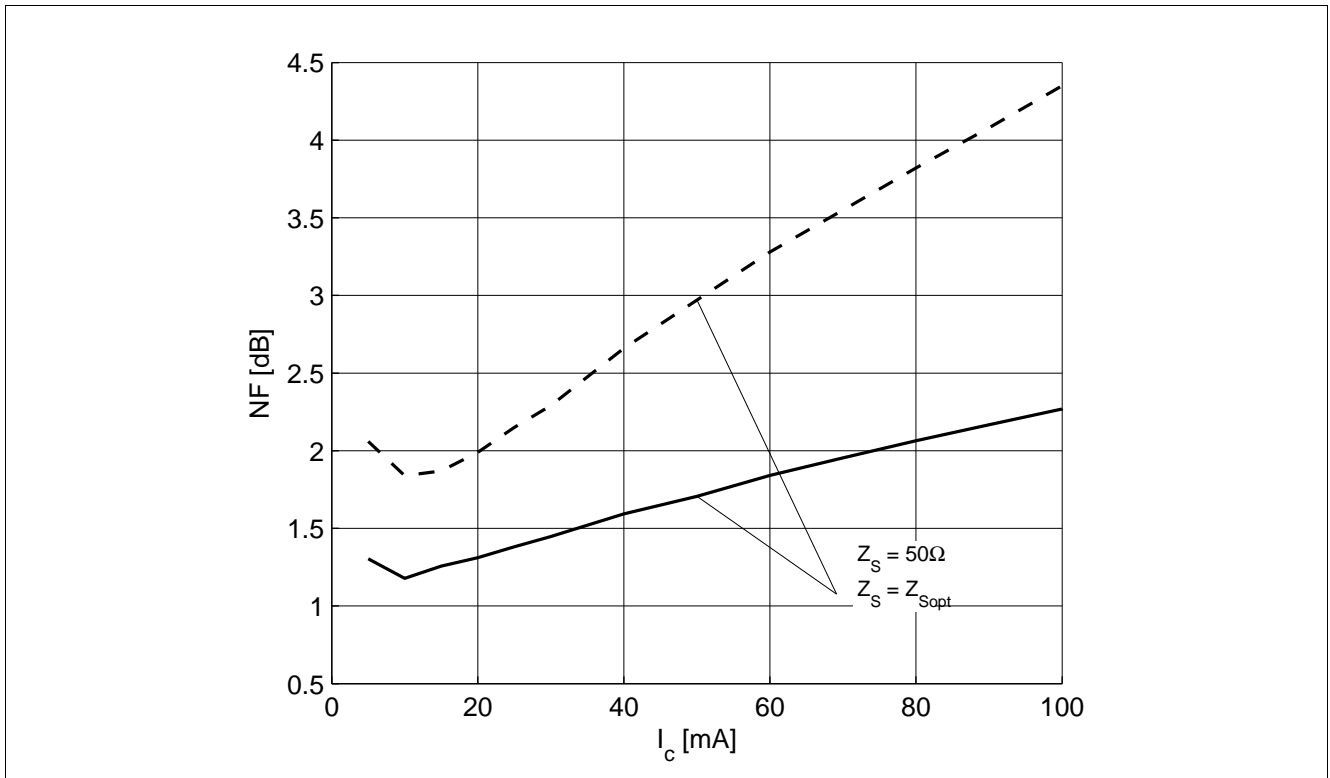


Figure 5-19 Comparison Noise Figure  $NF_{50} / NF_{min} = f(I_C)$ ,  $V_{CE} = 3\text{ V}$ ,  $f = 1.9\text{ GHz}$

Note: The curves shown in this chapter have been generated using typical devices but shall not be considered as a guarantee that all devices have identical characteristic curves.  $T_A = 25\text{ }^\circ\text{C}$ .

## 6 Simulation Data

For the SPICE Gummel Poon (GP) model as well as for the S-parameters (including noise parameters) please refer to our internet website: [www.infineon.com/rf.models](http://www.infineon.com/rf.models). Please consult our website and download the latest versions before actually starting your design.

You find the BFP450 SPICE GP model in the internet in MWO- and ADS-format, which you can import into these circuit simulation tools very quickly and conveniently. The model already contains the package parasitics and is ready to use for DC- and high frequency simulations. The terminals of the model circuit correspond to the pin configuration of the device.

The model parameters have been extracted and verified up to 10 GHz using typical devices. The BFP450 SPICE GP model reflects the typical DC- and RF-performance within the limitations which are given by the SPICE GP model itself.

## 7 Package Information SOT343

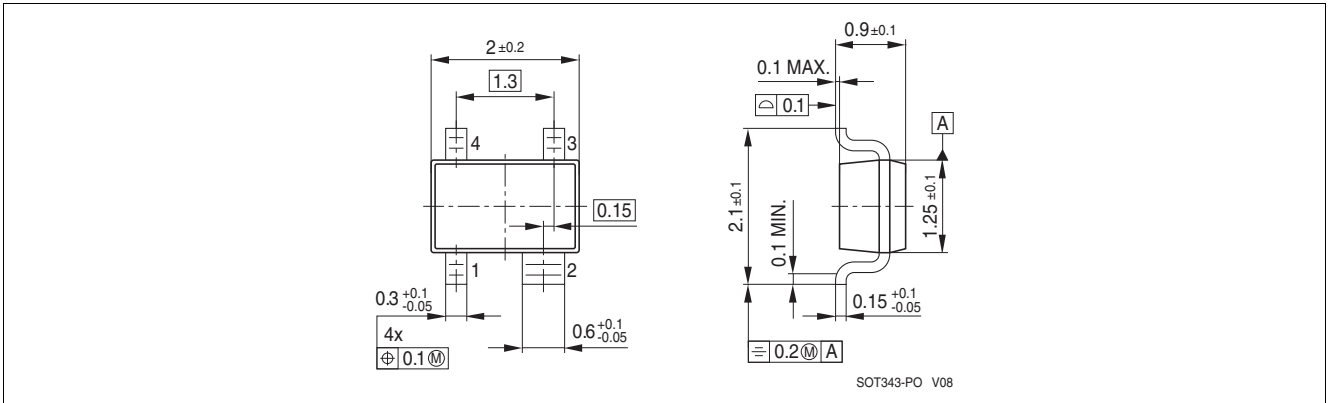


Figure 7-1 Package Outline

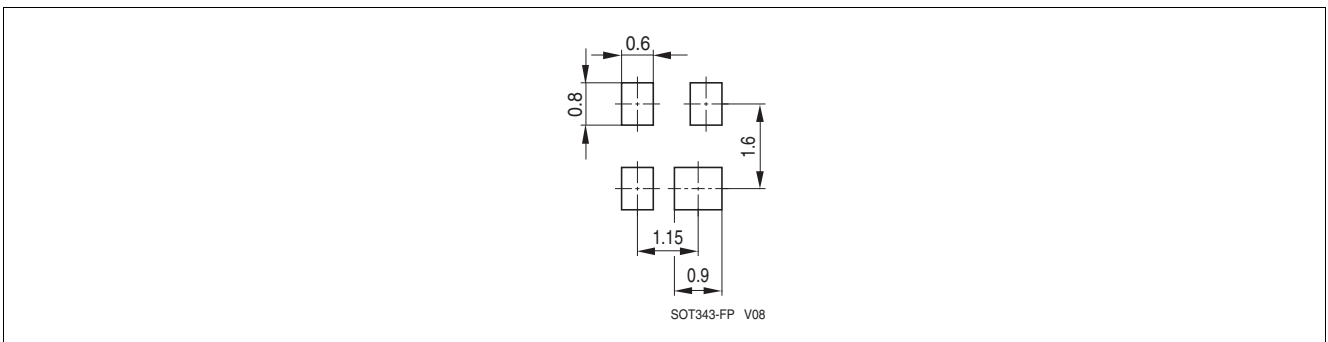


Figure 7-2 Package Footprint

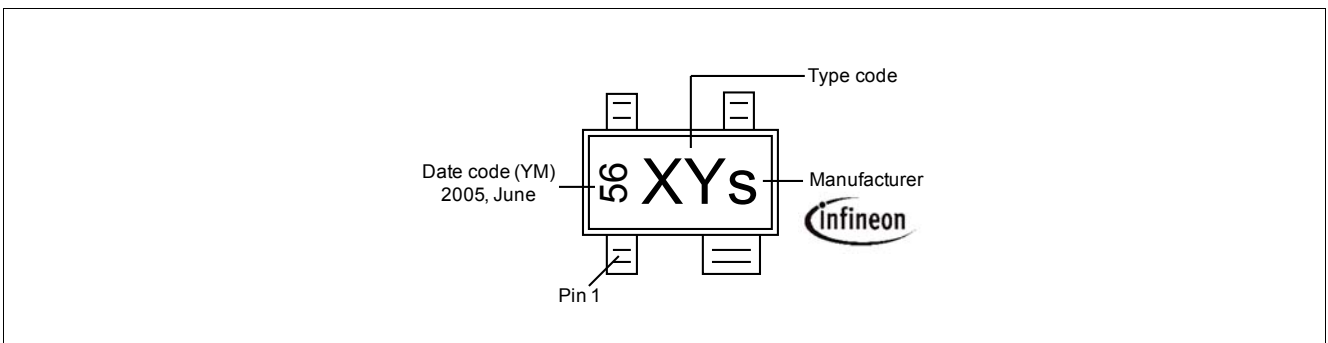


Figure 7-3 Marking Description (Marking BFP450: ANs)

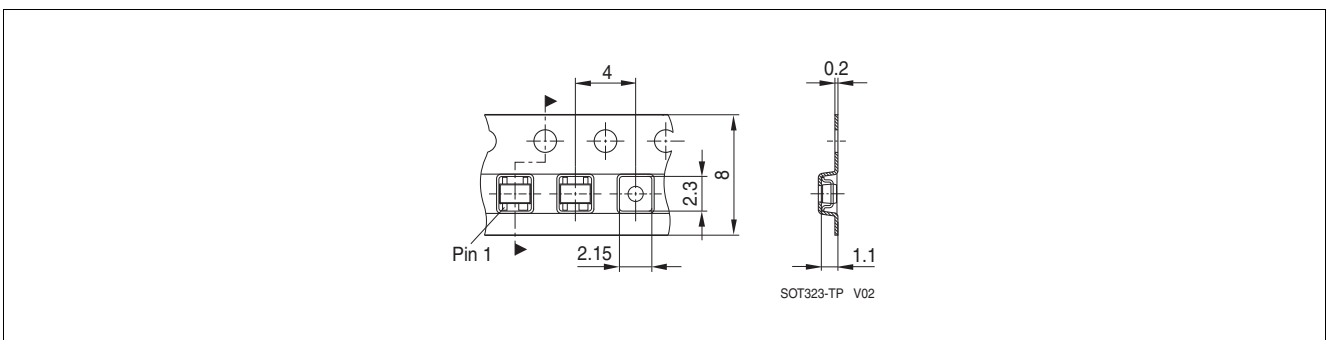


Figure 7-4 Tape Dimensions

[www.infineon.com](http://www.infineon.com)

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